



Electronic Filing System (EFS) Data Electronic Patent Application Submission USPTO Use Only

EFS ID:

63053

Application ID:

10813945

Title of Invention:

High-Density connection

between multiple circuit boards

First Named Inventor:

Douglas Wildes

Domestic/Foreign Application:

Domestic Application

Filing Date:

2004-03-30

Effective Receipt Date:

2004-06-22

Submission Type:

Information Disclosure

Statement

Filing Type:

Confirmation number:

5777

Attorney Docket Number:

134730

Total Fees Authorized:

Digital Certificate Holder: cn=Dennis Michael Flaherty,ou=Registered Attorneys,ou=Patent and

Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US Certificate Message Digest: 95d753cce719c7e82d2f8eb61f37ae73239f3a3d

O Jun 2 2 2004 SE

TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention

High-Density connection between multiple circuit boards

Application Number:

10/813945

Date:

2004-03-30

First Named Applicant:

Douglas Glenn

Confirmation Number:

5777

Attorney Docket Number: 134730

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Dennis M Flaherty Registered Number: 31159	/dennis flaherty/	Attorney

Documents being submitted

Files

us-ids

GERD134730-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

High-Density connection between multiple circuit boards

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First Named Applicant:

Douglas Wildes

Attorney Docket Number: 134730

Search string:

(6520789 or 6437557 or 6309223 or 6162065

or 5871362 or 5378161).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6520789	2003-02-18	Daughert, Jr. et al.			
	2	6437557	2002-08-20	Smith			
	3	6309223	2001-10-30	Wolfe			
	4	6162065	2000-12-19	Benham			
	5	5871362	1999-02-16	Campbell et al.			
	6	5378161	1995-01-03	Loder			

Signature

Examiner Name	Date		